



# **AND183HGP**

## InGaAIP High Brightness Green Light Emission T-1 3/4 Package (5 mm)

#### **Features**

- Peak wavelength ( $\lambda p = 574 \text{ nm}$ ) emission
- All plastic mold type, clear colorless lens
- Low drive current: 1 to 20 mA DC
- Excellent On-Off contrast ratio
- · Solid state reliability, long life
- Fast response time, capable of pulse operation
- High power luminous intensity

## Maximum Ratings (T = 25°C)

Characteristics	Symbol	Rating	Unit
Forward Current	I <sub>F</sub>	50	mA
Reverse Voltage	V <sub>R</sub>	4	V
Power Dissipation	P <sub>D</sub>	140	mW
Operating Temperature Range	T <sub>Opr</sub>	-40 to 85	°C
Storage Temperature Range	T <sub>Stg</sub>	-40 to 120	°C

### **Electro-Optical Characteristics (T = 25°C)**

Characteristics	Symbol	Test Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 20 mA	_	2.35	2.8	V
Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 4 V	_	_	50	μΑ
Luminous Intensity	I <sub>V</sub>	I <sub>F</sub> = 20 mA	850	2,500	-	mcd
Peak Emission Wavelength	Ι <sub>Ρ</sub>	I <sub>F</sub> = 20 mA	_	574	-	nm
Spectral Line Half Width	Δλ	I <sub>F</sub> = 20 mA	_	11	-	nm
Dominant Wavelength	λd	I <sub>F</sub> = 20 mA	_	571	-	nm
Full Viewing Angle	θ	I <sub>V</sub> = 1/2 Peak	_	8	_	degree

#### Precaution

Please be careful of the following:

- 1. Soldering temperature: 260°C max
  - Soldering time: 3 sec. max
  - Soldering portion of lead: up to 2 mm from the body of the device
- 2. The lead can be formed up to 5 mm from the body of the device without forming stress. Soldering should be performed after the lead forming.